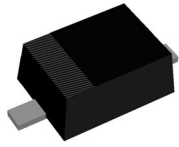
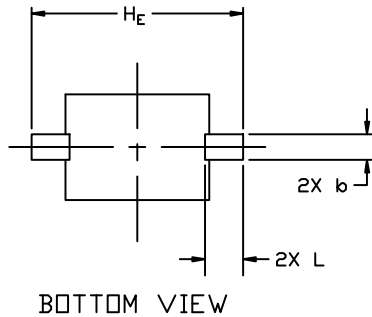
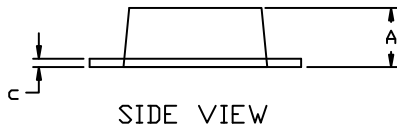
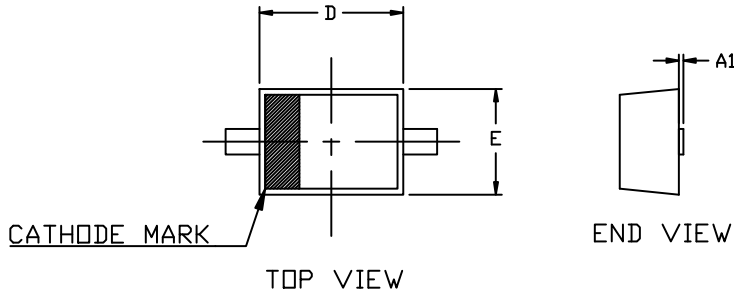


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



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CASE 477AB
ISSUE A

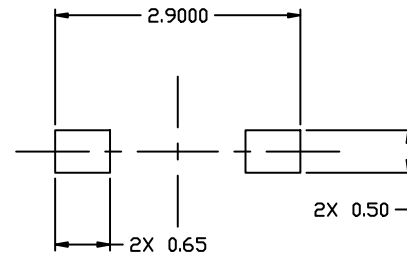
DATE 03 FEB 2023



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. LEAD THICKNESS INCLUDES LEAD FINISH.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.60	0.70	0.90
A1	0.00	0.05	0.10
b	0.25	0.30	0.35
c	0.05	0.10	0.20
D	1.60	1.70	1.80
E	1.15	1.25	1.35
HE	2.30	2.50	2.70
L	0.35	0.45	0.55



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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